PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Continuation of Glenn A. Rinne et al;

Application No. not yet assigned

Filed: concurrently herewith

For: LOW TEMPERATURE METHODS OF BONDING COMPONENTS AND

RELATED STRUCTURES

Date: March 2, 2004

Mail Stop PATENT APPLICATION Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Attached is a list of documents on form PTO-1449. Items 1-19 listed on the PTO-1449 were cited in parent application Serial No. 10/017,350, filed December 14, 2001. As the benefit of this application is claimed under 35 U.S.C. §120, no copies need to be furnished in accordance with 37 C.F.R. §1.98(d); however, copies will be furnished on request. It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and Section 609 of the MPEP.

No fee is believed due. However, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

Respectfully submitted,

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Joyce Paol

Substitute form 1449A/PTO				Complete if Known		
				Application Number	not yet assigned	
INFORM	ATION DISCL	OSURE		Filing Date	concurrently herewith	
STATEM	ENT BY APP	LICANT		First Named Inventor	Glenn A. Rinne	
				Group Art Unit		
(use as many sheets as necessary)				Examiner Name		
Sheet	1	of	1	Attorney Docket Number	9180-10CT	

Examiner	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited	Date of Publication of Cited	
Initials*		Number	Kind Code (if known)	Document	Document MM-DD-YYYY	
	1.	US-3,602,979		La Iacona, Felix P.	09/00/1971	
	2.	US-3,923,231		Catalano et al;	12/00/1975	
	3.	US-4,325,734		Burrage et al;	04/00/1982	
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	7.	US-5,392,982		Li, Chou H.	02/00/1995	
	8.	US-5,542,602		Gaynes et al;	08/00/1996	
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	11.	US-6,087,021		Gaynes et al;	07/00/2000	
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				Name of Patentee or Applicant of Cited	Date of Publication of Cited Document MM-DD-YYYY	Ť	
No.	Office	Number	Kind Code (if known)	Document			
	16.	JP 403234359A		Ogawa et al;	10/00/1991		
		OTHER	 R NON PATEN	T LITERATURE DOCUMENTS	<u> </u>	L	
17.	US 2002/0157247A1 Li (10/31/02)						
18.	US 2002/0074381A1 Rinne et al. (6-20-02).						
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Examiner Signature	Date Considered			

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.